Page I of	2 Pages [ ] Original	[ ] Substitute	[ ] Suppleme	ntal	Atty. Docket:
Co	mbined Declarati	on for Patent A	pplication a	nd Power of Att	orney
As a below-name	d inventor, I hereby declar	e that:			
and sole inventor	ost office address and citize (if only one name is listed nich is claimed and for whice	d below) or an original,	first and joint inv	entor (if plural names ar	
	BONDING PLASTIC MIC of which (check one)	RO CHIP	···		
[ ]	is attached hereto;	. d States under 35 U.S.C	C. §111 on	, as	
[X]	<ol> <li>was/will be filed in th (PCT) application,</li> </ol>	ie U.S. under 35 U.S.C PCT/ <u>KR2004/003337</u>	; filed on De	nto the U.S. national stag cember 17, 2004, e .S. Appln. No.	entry requested on
	date	* (* if known)			
and was amended	on	<del></del>		(if applicable).	
	(include dates of amen	dments under PCT Art. 1	9 and 34 if PCT)		-
amendment refer	and understand the contered to above; and I acknown to material to patentability	vledge the duty to disc	lose to the Patent		
	reign priority benefits und nt breeder's rights certifical S., listed below:				
	Application No.	Country	Filin	g Date (MM/DD/YYYY)	
	10-2003-0093443	KR_	<del></del>	12/18/2003	-
application design	gn priority above, I hereby nating a country other than fithe earliest application from	n the United States) or	for an inventor's	or plant breeder's certifi	icate, having a filing
	Non-Priority Application No	o. Countr	ry F	iling Date (MM/DD/YYYY	<b>9</b>
L bereby aloim the	e benefit under 35 U.S.C. §	110(a) of any United S	tates provisional a	nnlications listed helow	<del></del>
Thereby Claim the	•	cation No.	Filing Date (MM	• •	
PCT internationa application is not U.S.C. §112, I ad	e benefit under 35 U.S.C. l application(s) designating t disclosed in such U.S. ocknowledge the duty to disch became available betweention:	g the U.S., listed below r PCT international apsclose to the PTO all	and, insofar as the plication in the minformation which	ne subject matter of each nanner provided by the f is material to patentabi	of the claims of this first paragraph of 35 ility as defined in 37
Αţ	oplication No.	Filing Date (MM/DD/	YYYY)	Status (patented, pending,	abandoned)
As a named inve	entor, I hereby appoint the	e following registered	practitioners to p	rosecute this application	n and to transact all

All of the practitioners associated with Customer Number 001444

Direct all correspondence to the address associated with Customer Number 001444, which is presently:

business in the Patent and Trademark Office connected therewith:

BROWDY AND NEIMARK, P.L.L.C. 624 Ninth Street, N.W. Washington, D.C. 20001-5303 (202) 628-5197

Page 2 of 2 Pages		Atty. Docket:
Title: METHOD FOR BONDING PLASTIC MIC	RO CHIP	
J.S. Application filed	, Serial No.	
PCT Application filed December 17, 2004	Serial No. PCT/KR2004/003337	

The undersigned hereby authorizes the U.S. Attorneys or Agents appointed herein to accept and follow instructions from Kim, Choi & Lim as to any action to be taken in the U.S. Patent and Trademark Office regarding this application without direct communication between the U.S. Attorneys or Agents and the undersigned. In the event of a change of the persons from whom instructions may be taken, the U.S. Attorneys or Agents appointed herein will be so notified by the undersigned.

I hereby further declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. §1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

FULL NAME OF FIRST INVENTOR	INVENTOR'S SIGNATURE		DATE				
Jun Keun CHANG	In The Chay		30/05/06				
RESIDENCE		CITIZENSHIP	,				
Seoul, Republic of Korea		Republic of Korea					
POST OFFICE ADDRESS							
501, Grandciel Villa, Bangbae 4-Dong, Seocho-Ku, Seoul, 137-064, Republic of Korea							
FULL NAME OF SECOND JOINT INVENTOR	INVENTOR'S SIGNATURE	7	DATE.				
Dae Sung HUR		/	no fot fob				
RESIDENCE		CITIZENSHIP					
Kyungsan-Si, Kyungsangbuk-Do, Republic of Kor	Republic of Korea						
POST OFFICE ADDRESS							
116-188, Keumrac 4Ri, Hayang-Eup, Kyungsan-Si, Kyungsangbuk-Do, 712-905, Republic of Korea							
FULL NAME OF THIRD JOINT INVENTOR	INVENTOR'S SIGNATURE	7	DATE				
Chanil CHUNG	1000		30/05/06				
RESIDENCE		CITIZENSHIP	•				
Uiwang-Si, Kyunggi-Do, Republic of Korea	Republic of Korea						
POST OFFICE ADDRESS							
106-2201, Samsung Raemian Apartment, Naeson-Dong, Uiwang-Si, Kyunggi-Do, 437-080, Republic of Korea							
FULL NAME OF FOURTH JOINT INVENTOR	INVENTOR'S SIGNATURE	)	DATE.				
Jun Ha PARK			39 05/56				
RESIDENCE		CITIZENSHIP					
Suwon-Si, Kyunggi-Do, Republic of Korea		Republic of Korea					
POST OFFICE ADDRESS							
803-1504, Byukjukgol Doosan Apartment, Youngt	ong-Dong, Paldal-Ku, Suwon-	Si, Kyunggi-Do	,				
442-470, Republic of Korea							
FULL NAME OF FIFTH JOINT INVENTOR	INVENTOR'S SAGNATURE		DATE				
Han Sang JO	to Chuquee	f l	30/05/00				
RESIDENCE		CITIZENSHIP	,				
Anyang-Si, Kyunggi-Do, Republic of Korea	Republic of Korea						
POST OFFICE ADDRESS							
103-405, Dream Village Life Apartment, Kuiin-Dong, Dongan-Ku, Anyang-Si, Kyunggi-Do,							
431-708, Republic of Korea			•				
FULL NAME OF SIXTH JOINT INVENTOR	INVENTOR'S SIGNATURE		DATE				
RESIDENCE		CITIZENSHIP					
POST OFFICE ADDRESS							

ALL INVENTORS MUST REVIEW APPLICATION AND DECLARATION BEFORE SIGNING. ALL ALTERATIONS MUST BE INITIALED AND DATED BY ALL INVENTORS PRIOR TO EXECUTION. NO ALTERATIONS CAN BE MADE AFTER THE DECLARATION IS SIGNED. ALL PAGES OF DECLARATION MUST BE SEEN BY ALL INVENTORS.